

FIELD PROGRAMMABLE PLATFORM ARRAY

ABSTRACT

The present invention is directed to a field programmable platform array (FPPA). In an exemplary aspect of the present invention, a method for providing field programmable platform array units (PAUs) may include the following steps. First, N by M array of platform array units may be cut from a field programmable platform array wafer according to a customer's order, where N and M are positive integers. The field programmable platform array wafer is a wafer with all silicon layers and metal layers already built and includes a plurality of platform array units. The platform array units may be field programmable by a customer, and each platform array unit may include at least one core and at least one processor. Interconnect between any two of the platform array units may be pre-routed on chip. Next, the N by M array of platform array units may be packaged and tested. After the N by M array of platform array units are delivered to the customer, the N by M array of platform array units may be field programmed by the customer.